

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. – 15. (Canceled)
16. (currently amended) A plastic injected part ~~with~~ comprising
a printed circuit board ~~that exhibits;~~
at least one contact element for connecting with a mating contact ~~, where the contact~~
~~element is secured to the circuit board, and~~
a plastic layer, which is applied to at least one side of the circuit board,
~~where~~ wherein the contact element runs from the circuit board through the plastic
layer and projects from this plastic layer to connect the mating contact,
~~characterized in that~~
the plastic extends from the plastic layer outward and laterally as a pot shaped
housing wall of a housing, the plastic layer and housing wall forming a contiguous structure,
and
the plastic layer and the housing wall ~~are~~ produced from the same material.
17. (currently amended) A plastic injected part according to claim ~~15~~ 16, in which
the plastic layer is applied to one or both sides of the circuit board,
in which the plastic layer is a thermoplastic material with a melting point
greater than 80° C., ~~in which the contact element is soldered to the circuit board, in~~
~~which the circuit board consists of an epoxide fiberglass laminate with an interlaced~~
~~resin system, and~~
in which at least one conductor is positioned on the surface of the circuit
board and the plastic layer covers the conductor and an adjacent surface area of the
circuit board.

18. – 20. (Canceled)

21. (new) A plastic injected part according to claim 17, in which the circuit board consists of an epoxide fiberglass laminate with an interlaced resin system.

22. (new) A plastic injected part according to claim 17, in which the circuit board consists of an epoxide fiberglass laminate with an interlaced resin system and includes the contact element solder connected to the circuit board.

23. (new) A plastic injected part according to claim 16, in which
the plastic layer is applied to one or both sides of the circuit board,
in which the plastic layer is a thermoplastic material with a melting point
greater than 350° C., and
in which at least one conductor is positioned on the surface of the circuit
board and the plastic layer covers the conductor and an adjacent surface area of the
circuit board.

24. (new) A plastic injected part according to claim 23, in which the circuit board consists of an epoxide fiberglass laminate with an interlaced resin system.

25. (new) A plastic injected part according to claim 23, in which the circuit board consists of an epoxide fiberglass laminate with an interlaced resin system and includes the contact element solder connected to the circuit board.